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Part Number: [5020783310](#)
Status: **Active**
Description: 0.25mm (.010") Pitch Easy-On™ Type FPC Connector, 1.00mm (.039") Mated Height, Right Angle, SMT, Bottom Contact Style, 33 Circuits, Halogen Free

Documents:

[3D Model](#) [Product Specification PS-502078-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family FFC/FPC Connectors
 Series [502078](#)
 Product Name Easy-On™

Physical

Circuits (Loaded) 33
 Contact Position Bottom
 Durability (mating cycles max) 10
 Entry Angle 90° Angle
 Mated Height (in) 0.039 In
 Mated Height (mm) 1.00 mm
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Number of Rows 1
 Orientation Right Angle
 PCB Locator No
 PCB Retention Yes
 Packaging Type Embossed Tape on Reel
 Pitch - Mating Interface (in) 0.010 In
 Pitch - Mating Interface (mm) 0.25 mm
 Polarized to PCB Yes
 Stackable No
 Temperature Range - Operating -20°C to +85°C
 Termination Interface: Style Surface Mount
 Wire/Cable Type FPC only

Electrical

Current - Maximum per Contact 0.2A
 Voltage - Maximum 50V

Material Info

Reference - Drawing Numbers

Product Specification PS-502078-002, RPS-502078-006, RPS-502078-007
 Sales Drawing SD-502078-003, SD-502078-004

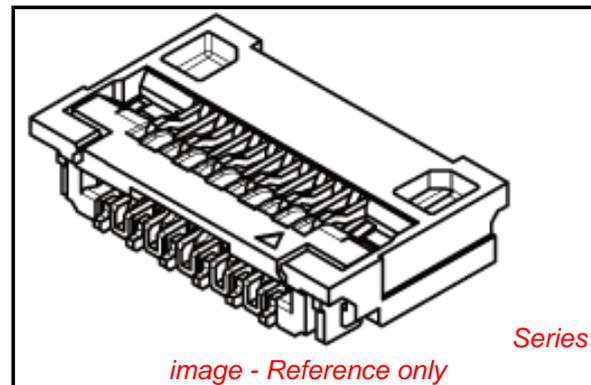


image - Reference only

EU RoHS

**ELV and RoHS
 Compliant**
REACH SVHC
 Not Reviewed
**Halogen-Free
 Status**
Not Reviewed

China RoHS

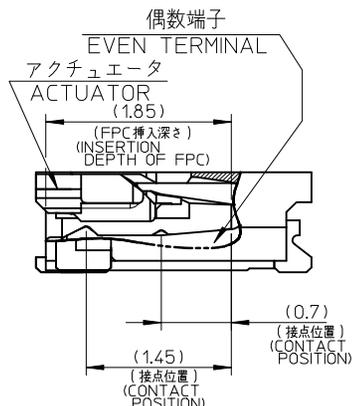
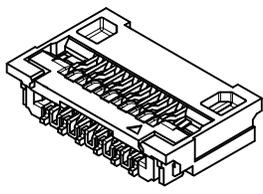
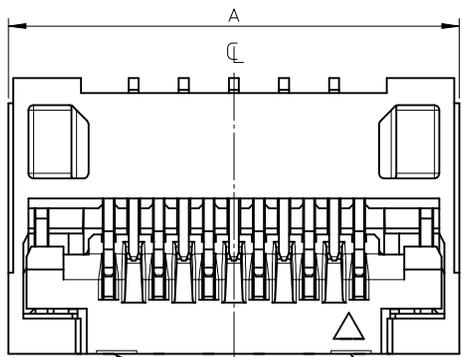


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 environmental compliance?**

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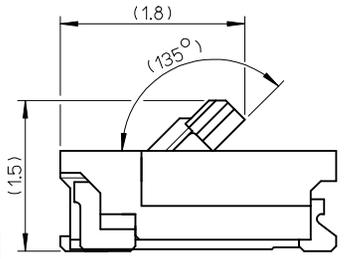
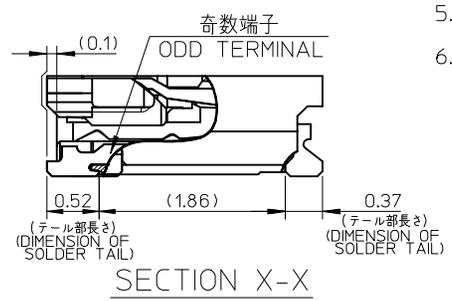
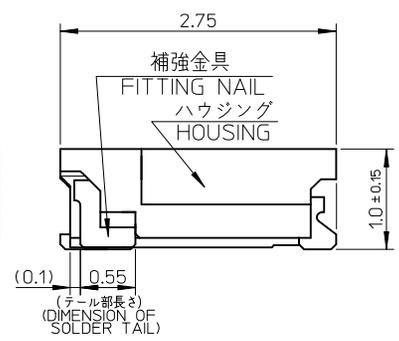
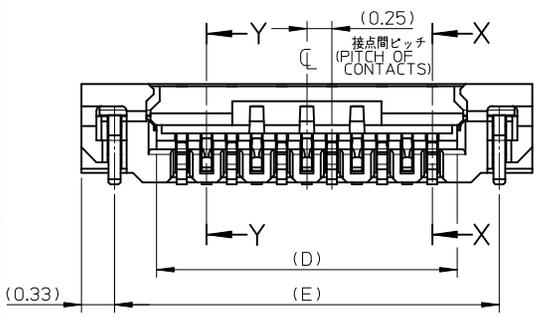
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Search Parts in this Series
[502078Series](#)

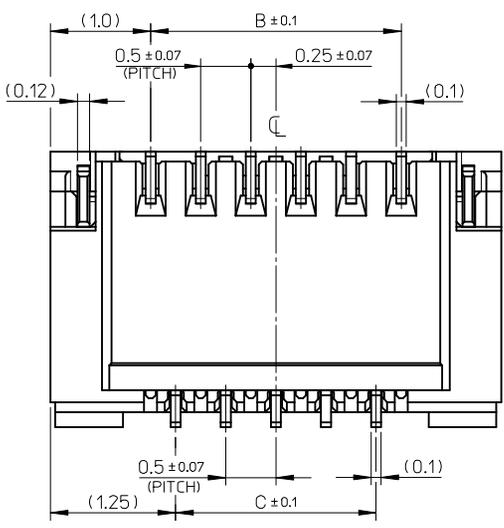


注記 NOTES

1. 使用材料 MATERIALS
 - ハウジング : 耐熱性樹脂(UL94V-0、ベージュ)
 - アクチュエータ : 耐熱性樹脂(UL94HB、黒色)
 - 奇数端子 : 銅合金、ニッケル下地、金メッキ
 - 偶数端子 : 銅合金、ニッケル下地、金メッキ
 - 補強金具 : 銅合金、ニッケル下地、スズメッキ
 - HOUSING : G.F. HEAT RESISTANCE PLASTIC (BEIGE)
 - ACTUATOR : G.F. HEAT RESISTANCE PLASTIC (BLACK)
 - ODD TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 - EVEN TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 - FITTING NAIL : COPPER ALLOY, Tin OVER Nickel PLATING
- △ 端子、補強金具のコプラナリティーは 0.1 以下とする
COPLANARITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
3. 一般公差 : ±0.3
GENERAL TOLERANCES: ±0.3
△ アクチュエータの図示箇所にゲート逃げの凹みがあります
THERE ARE DENT SHAPES AT ACTUATOR FOR MOLDING GATE
5. ELV 及び RoHS 適合品
ELV AND ROHS COMPLIANT
6. 塩素系・臭素系難燃剤非使用
CHLORINATED AND BROMINATED FLAME RETARDANTS FREE

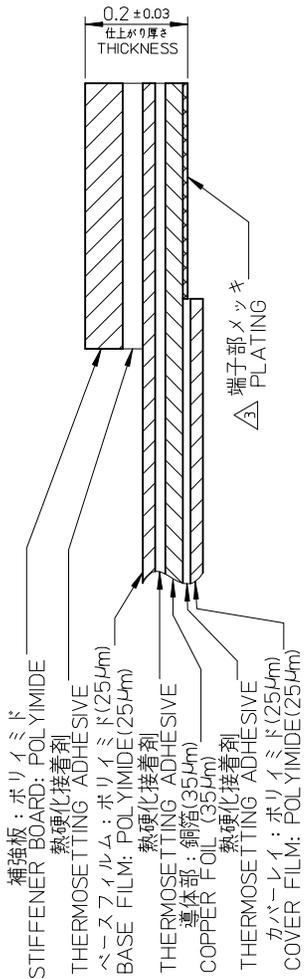


アクチュエータ開放位置
ACTUATOR OPENING POSITION

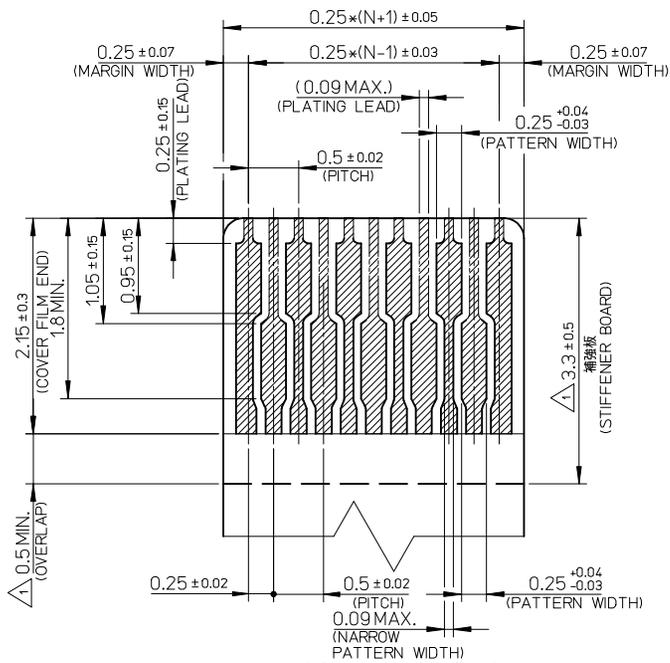


13.84	13	12	12.5	14.5	502078-5110	502078-5118	51
10.84	10	9	9.5	11.5	502078-3910	502078-3918	39
9.34	8.5	7.5	8	10	502078-3310	502078-3318	33
7.34	6.5	5.5	6	8	502078-2510	502078-2518	25
6.34	5.5	4.5	5	7	502078-2110	502078-2118	21
5.34	4.5	3.5	4	6	502078-1710	502078-1718	17
E	D	C	B	A	ORDER NO.	MATERIAL NO.	CKT.=N

RELEASED EC NO.: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	20:1	METRIC	◎ □
	10 UNDER	± ---	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	± ---	YFUJITA	2008/12/15	0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE	
30 OVER	± ---	CHECKED BY	DATE	MATERIAL NO.		SHEET NO.
		TKANEKO	2008/12/15	502078-**18		1 OF 2
		APPROVED BY	DATE	MODEL NO.		
		AHORINO	2008/12/15	502078-1710		
		MATERIAL NO.		DOCUMENT NO.		
				SEE CHART		
				SD-502078-003		
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



FPC 構成材料例
EXAMPLE OF FPC COMPOSITION MATERIAL

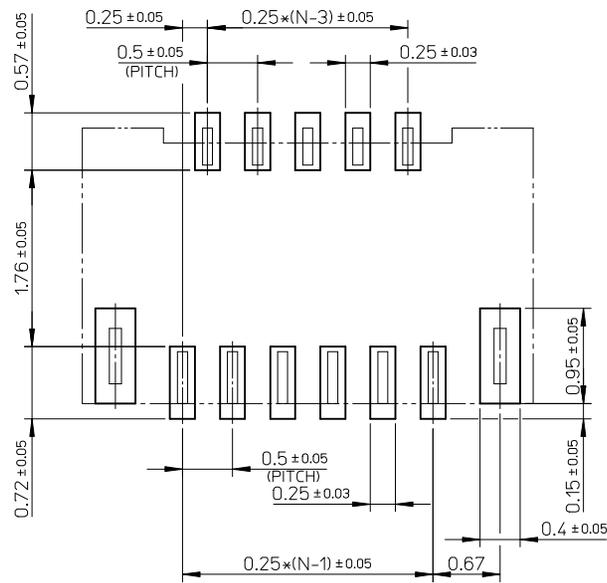


適合するFPC 推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(端子部仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

注記 NOTES

- △ 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT BE SECURED AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 2 推奨ペースト厚 : 100μm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100μm
RECOMMEND SCREEN OPEN RATIO : 80%



FPC挿入側
FPC INSERSION SIDE
参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS (REF.)

4 FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

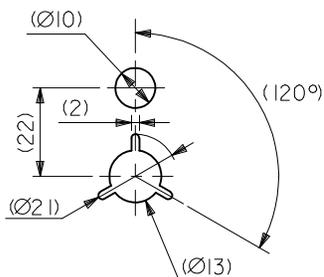
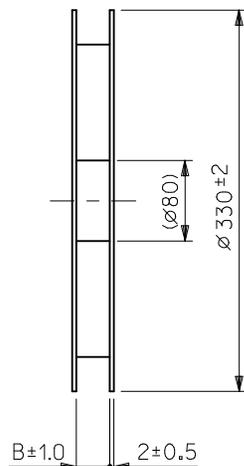
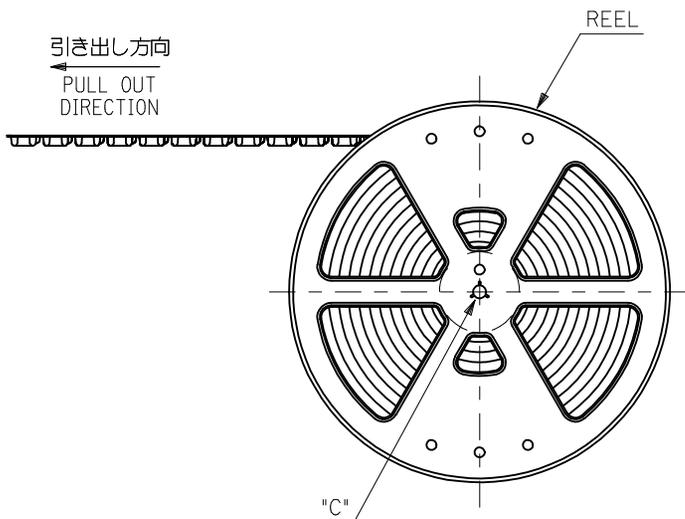
- △ FPCパターンのメッキ仕様は
金メッキ : 0.1μm以上
下地ニッケルメッキ : 2~6μm
FPC PATTERN PLATING
GOLD PLATING : 0.1μm MINIMUM
NICKEL UNDER PLATING : 2~6μm

RELEASED EC NO: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE		
	10 OVER 30 UNDER	± ---	CHECKED BY TKANEKO	DATE 2008/12/15	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY AHORINO	DATE 2008/12/15	DOCUMENT NO. SD-502078-003		
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1 OF 2		SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記 NOTES

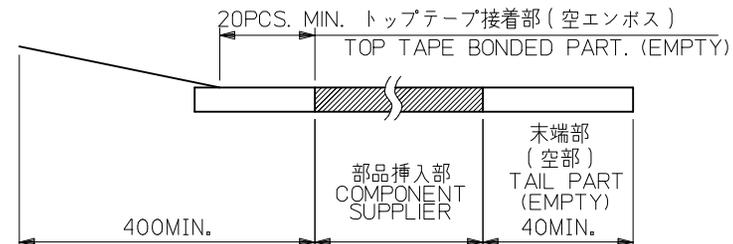
- 製品詳細寸法については図面 SD-502078-003 を参照下さい。
RE DETAILED DIMENSION, SEE SD-502078-003
- 梱包数量：3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

引き出し方向
PULL OUT
DIRECTION



DETAIL "C"

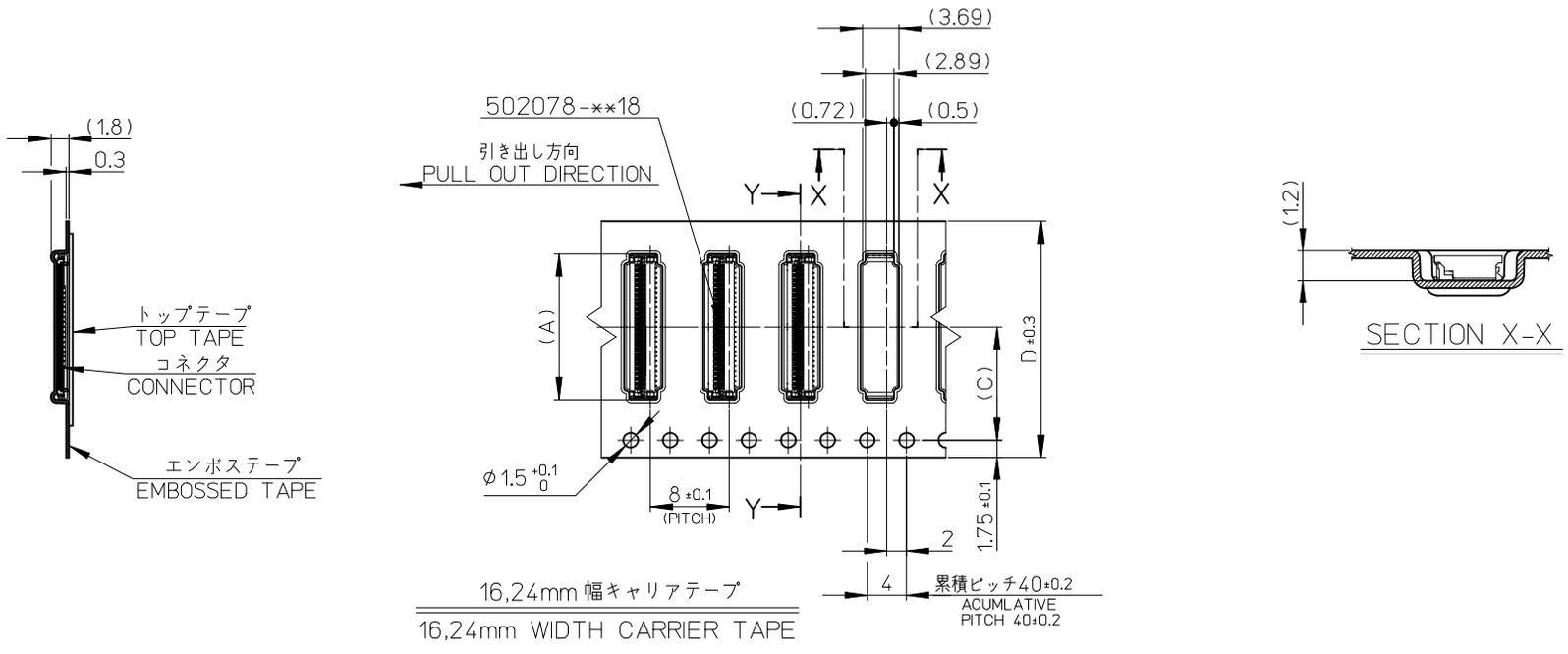
引き出し方向
PULL OUT
DIRECTION



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

MODEL NO. 502078-**10

RELEASED EC NO: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 FPC CONN E/O HSG ASSY EMBOSSED TAPE PACKAGE			
	10 OVER 30 UNDER	±0.25	CHECKED BY TKANEKO	DATE 2008/12/15				
	30 OVER	±0.3	APPROVED BY AHORINO	DATE 2008/12/15	MOLEX INCORPORATED			
	ANGULAR ±1 °		MATERIAL NO. SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



24	11.5	25.4	14.8	502078-5110	51
			11.8	502078-3910	39
			10.3	502078-3310	33
			8.3	502078-2510	25
			7.3	502078-2110	21
16	7.5	17.4	6.3	502078-1710	17
D キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	製品番号 MATERIAL NO.	極数 CKT.
			MODEL NO.		502078-**-10

RELEASED EC NO: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15 REV: 0	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3 ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		DRAWN BY YFUJITA		DATE 2008/12/15		TITLE 0.25MM FPC CONN E/O HSG ASSY EMBOSSED TAPE PACKAGE			
		CHECKED BY TKANEKO		DATE 2008/12/15		APPROVED BY AHORINO			
		APPROVED BY AHORINO		DATE 2008/12/15		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-502078-004	
		MATERIAL NO. SEE CHART		DATE 2008/12/15		MATERIAL NO. SEE CHART		SHEET NO. 2 OF 2	

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

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